

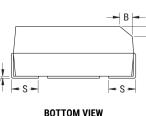
T598B227M2R5ATE025

T598, Tantalum, Polymer Tantalum, 220 uF, 20%, 2.5 VDC, SMD, Polymer, Molded, Low ESR, AEC-Q200, 25 mOhms, 3528, Height Max = 2.1mm

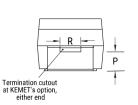
CATHODE (-) END VIEW

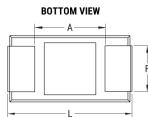


ANODE (+) END VIEW



SIDE VIEW





Click here for the 3D model.

Footprint 3528 L 3.5mm +/-0.2mm W 2.8mm +/-0.2mm H 1.9mm +/-0.2mm T 0.13mm REF S 0.8mm +/-0.3mm F 2.2mm +/-0.3mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF X 0.1mm +/-0.1mm	Dimensions	,
W 2.8mm +/-0.2mm H 1.9mm +/-0.2mm T 0.13mm REF S 0.8mm +/-0.3mm F 2.2mm +/-0.1mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	Footprint	3528
H 1.9mm +/-0.2mm T 0.13mm REF S 0.8mm +/-0.3mm F 2.2mm +/-0.1mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	L	3.5mm +/-0.2mm
T 0.13mm REF S 0.8mm +/-0.3mm F 2.2mm +/-0.1mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	W	2.8mm +/-0.2mm
S 0.8mm +/-0.3mm F 2.2mm +/-0.1mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	Н	1.9mm +/-0.2mm
F 2.2mm +/-0.1mm A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	Т	0.13mm REF
A 1.1mm MIN B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	S	0.8mm +/-0.3mm
B 0.4mm +/-0.15mm P 0.5mm REF R 1mm REF	F	2.2mm +/-0.1mm
P 0.5mm REF R 1mm REF	A	1.1mm MIN
R 1mm REF	В	0.4mm +/-0.15mm
	Р	0.5mm REF
X 0.1mm +/-0.1mm	R	1mm REF
,	Х	0.1mm +/-0.1mm

Т·

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	2000

T598
Polymer Tantalum
SMD Chip
SMD, Polymer, Molded, Low ESR, AEC-Q200
Automotive
Yes
Tin
AEC-Q200
Yes
94.9 mg
52 Weeks
3

Specifications	
Capacitance	220 uF
Capacitance Tolerance	20%
Voltage DC	2.5 VDC (105C), 1.68 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Humidity	85C, 85% RH, load, 1000 Hours
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
Resistance	25 mOhms (100kHz 25C)
Ripple Current	2320 mA (rms, 100kHz 45C), 1624 mA (rms, 105C), 580 mA (rms, 125C)
Leakage Current	55 uA (5min 25°C)

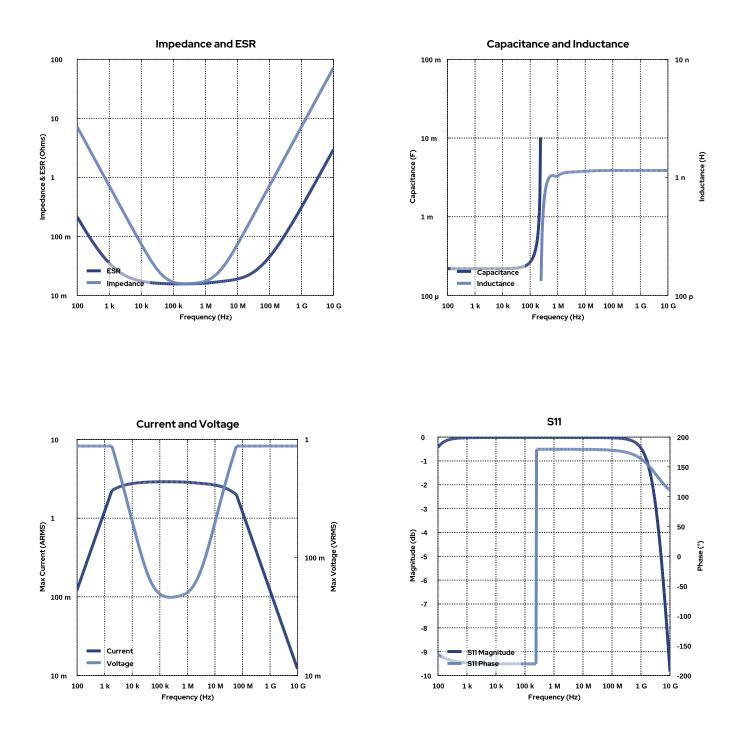
Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.



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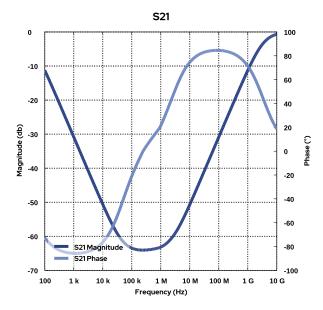
Simulations

For the complete simulation environment please visit K-SIM.





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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance. The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other
- harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

单击下面可查看定价,库存,交付和生命周期等信息

>>KEMET(基美)